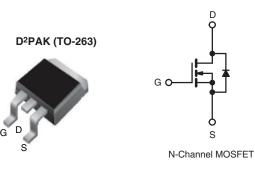
SiHB12N60E





E Series Power MOSFET

PRODUCT SUMMARY					
V _{DS} (V) at T _J max.	650				
R _{DS(on)} max. at 25 °C (Ω)	$V_{GS} = 10 V$	0.38			
Q _g max. (nC)	58				
Q _{gs} (nC)	6				
Q _{gd} (nC)	13				
Configuration	le				



FEATURES

- Low figure-of-merit (FOM) Ron x Qg
- Low input capacitance (Ciss)
- Reduced switching and conduction losses
- Ultra low gate charge (Q_q)
- Avalanche energy rated (UIS)
- Material categorization: for definitions of compliance please see <u>www.vishay.com/doc?99912</u>

APPLICATIONS

- Server and telecom power supplies
- Switch mode power supplies (SMPS)
- Power factor correction power supplies (PFC)
- Lighting
 - High-intensity discharge (HID)
 - Fluorescent ballast lighting
- Industrial
 - Welding
 - Induction heating
 - Motor drives
 - Battery chargers
 - Renewable energy
 - Solar (PV inverters)

ORDERING INFORMATION	
Package	D ² PAK (TO-263)
Lead (Pb)-free and Halogen-free	SiHB12N60E-GE3

ABSOLUTE MAXIMUM RATINGS (T _C :	= 25 °C, unl	ess otherwis	se noted)		
PARAMETER	SYMBOL	LIMIT	UNIT		
Drain-Source Voltage	V _{DS}	600	v		
Gate-Source Voltage	V _{GS}	± 30			
Continuous Drain Current (T. 150 °C)	V _{GS} at 10 V	T _C = 25 °C T _C = 100 °C	- I _D	12	
Continuous Drain Current (T _J = 150 °C)	V _{GS} at 10 V	T _C = 100 °C		7.8	A
Pulsed Drain Current ^a	I _{DM}	27			
Linear Derating Factor		1.2	W/°C		
Single Pulse Avalanche Energy ^b		E _{AS}	117	mJ	
Maximum Power Dissipation		PD	147	W	
Operating Junction and Storage Temperature Range	T _J , T _{stg}	-55 to +150	°C		
Drain-Source Voltage Slope	125 °C	-l) / / -lt	70		
Reverse Diode dV/dt ^d		dV/dt	5	V/ns	
Soldering Recommendations (Peak Temperature) ^c		300	°C		

Notes

a. Repetitive rating; pulse width limited by maximum junction temperature.

b. $V_{DD} = 50$ V, starting $T_J = 25$ °C, L = 11.6 mH, $R_g = 25 \Omega$, $I_{AS} = 4.5$ A.

c. 1.6 mm from case.

d. $I_{SD} \leq I_D,\,dI/dt$ = 100 A/µs, starting T_J = 25 °C.

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Vishay Siliconix

PARAMETER	SYMBOL	TYP.	TYP. MAX.			UNIT		
Maximum Junction-to-Ambient	R _{thJA}	-	- 62					
Maximum Junction-to-Case (Drain)	R _{thJC}	-	0.85		°C/W			
SPECIFICATIONS ($T_J = 25 \ ^{\circ}C_{,1}$	unless otherw	ise noted)						
PARAMETER	SYMBOL	1	T CONDITIONS	MIN.	TYP.	MAX.	UNI	
Static	0111202					in da	0.11	
Drain-Source Breakdown Voltage	V _{DS}	Vee	600	-	-	V		
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_J$		= 0 V, I _D = 250 μA e to 25 °C, I _D = 1 mA	-	0.71	-	V/°C	
Gate-Source Threshold Voltage (N)	V _{GS(th)}		$V_{DS} = V_{GS}, I_D = 250 \ \mu A$		-	4	V	
	• GS(III)		$V_{\text{DS}} = V_{\text{GS}}, \text{ ID} = 230 \mu\text{A}$ $V_{\text{GS}} = \pm 20 \text{V}$		_	± 100	nA	
Gate-Source Leakage	I _{GSS}		-	-	± 100	μA		
			$V_{GS} = \pm 30 V$ = 600 V, $V_{GS} = 0 V$	-	-	1	- μA	
Zero Gate Voltage Drain Current	I _{DSS}		$V_{\rm r}, V_{\rm GS} = 0 \text{ V}, \text{ T}_{\rm J} = 125 \text{ °C}$	-	-	10		
Drain-Source On-State Resistance	R _{DS(on)}	V _{GS} = 10 V	$I_{\rm D} = 6 {\rm A}$	-	0.32	0.38	Ω	
Forward Transconductance	9fs		= 40 V, I _D = 8 A	-	3.8	-	S	
Dynamic	4		-	_ I	ļ	Į		
Input Capacitance	C _{iss}		V _{GS} = 0 V,		937	-		
Output Capacitance	C _{oss}		$V_{DS} = 100 V,$	-	53	-	1	
Reverse Transfer Capacitance	C _{rss}		f = 1 MHz		5	-	− □ pF	
Effective Output Capacitance, Energy Related ^a	C _{o(er)}		V_{DS} = 0 V to 480 V, V_{GS} = 0 V		41	-		
Effective Output Capacitance, Time Related ^b	C _{o(tr)}	$ V_{DS} = 0$ V			136	-		
Total Gate Charge	Qg			-	29	58	nC	
Gate-Source Charge	Q _{gs}	$V_{GS} = 10 V$	$I_D = 6 A, V_{DS} = 480 V$	-	6	-		
Gate-Drain Charge	Q _{gd}			-	13	-		
Turn-On Delay Time	t _{d(on)}			-	14	28		
Rise Time	t _r	Voo	= 480 V, I _D = 6 A,	-	19	38	ns	
Turn-Off Delay Time	t _{d(off)}	V _{GS} =	$= 10 \text{ V}, \text{ R}_{g} = 9.1 \Omega$	-	35	70		
Fall Time	t _f			-	19	38]	
Gate Input Resistance	R _g	f = 1 MHz, open drain		-	1.1	-	Ω	
Drain-Source Body Diode Characterist	ics							
Continuous Source-Drain Diode Current	I _S	MOSFET sym showing the	MOSFET symbol showing the integral reverse p - n junction diode		-	12		
Pulsed Diode Forward Current	I _{SM}	°,			-	48	A	
Diode Forward Voltage	V _{SD}	T _J = 25 °	C, I _S = 6 A, V _{GS} = 0 V	-	-	1.2	V	
Reverse Recovery Time	t _{rr}			-	350	-	ns	
Reverse Recovery Charge	Q _{rr}		$100 \text{ A/W} = 1_{\text{S}} = 6 \text{ A},$	-	4	-	μC	
Reverse Recovery Current	I _{RRM}	dl/dt = 100 A/µs, V _R = 25 V		-	19		A	

Notes

a. $C_{oss(er)}$ is a fixed capacitance that gives the same energy as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DSS} .

b. $C_{oss(tr)}$ is a fixed capacitance that gives the same charging time as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DSS} .



SiHB12N60E

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TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

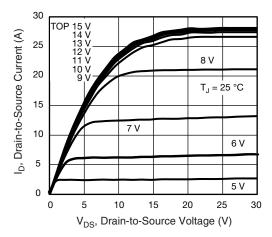


Fig. 1 - Typical Output Characteristics

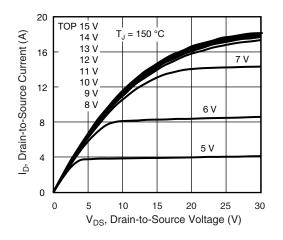
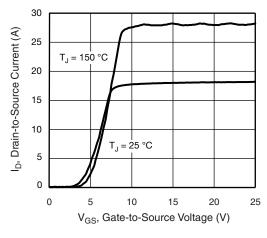


Fig. 2 - Typical Output Characteristics





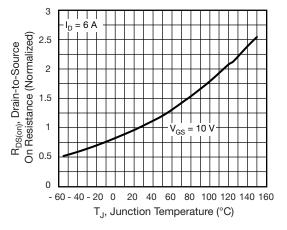


Fig. 4 - Normalized On-Resistance vs. Temperature

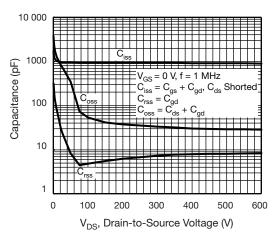


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

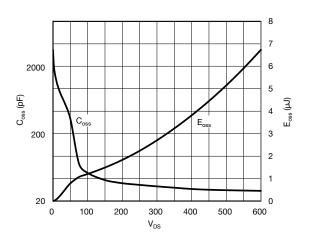


Fig. 6 - C_{oss} and E_{oss} vs. V_{DS}

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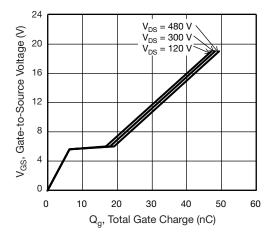


Fig. 7 - Typical Gate Charge vs. Gate-to-Source Voltage

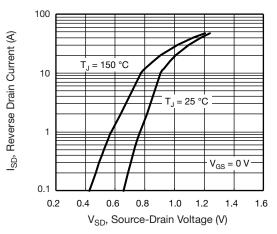


Fig. 8 - Typical Source-Drain Diode Forward Voltage

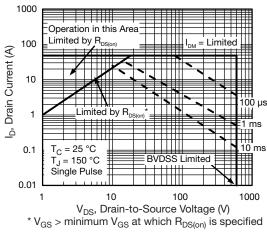


Fig. 9 - Maximum Safe Operating Area

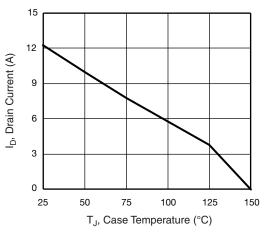


Fig. 10 - Maximum Drain Current vs. Case Temperature

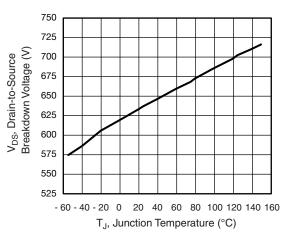
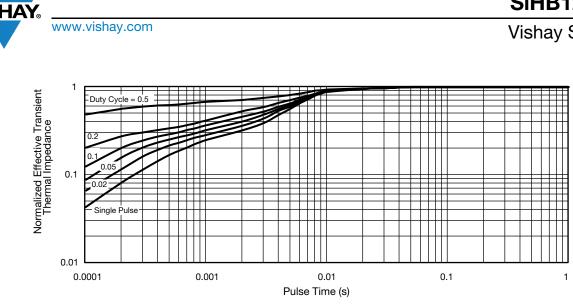


Fig. 11 - Temperature vs. Drain-to-Source Voltage

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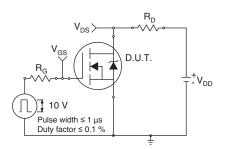


Fig. 13 - Switching Time Test Circuit

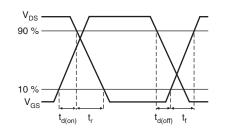
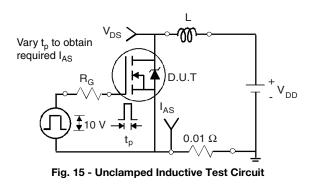


Fig. 14 - Switching Time Waveforms



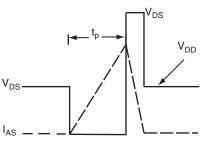


Fig. 16 - Unclamped Inductive Waveforms

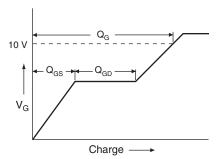


Fig. 17 - Basic Gate Charge Waveform

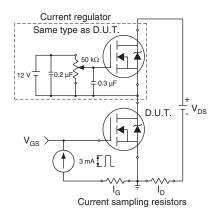


Fig. 18 - Gate Charge Test Circuit

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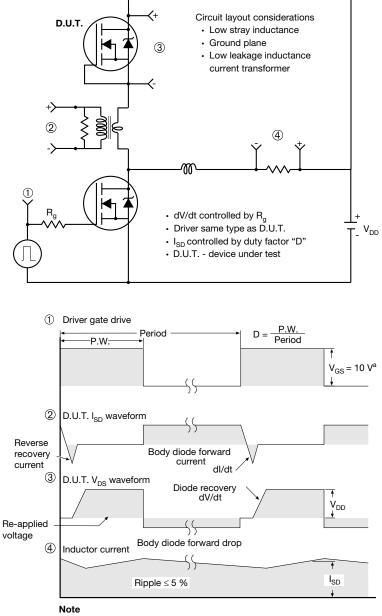
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Peak Diode Recovery dV/dt Test Circuit



a. $V_{GS} = 5 V$ for logic level devices

Fig. 19 - For N-Channel

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H

A1

B

Gauge plane

L3

Detail "A" Rotated 90° CW scale 8:1

0° to 8° **Vishay Siliconix**

Seating plane

TO-263AB (HIGH VOLTAGE)

∕3 ⁄4 A

н

∕₅∖

Detail A

(Datum A)

D

 $\underline{4}$ 11

	2	-	Y 2 x b2 2 x b ⊕ 0.010 @ A(■ ating 5 b1, b b1, b b1, b c) c) c) c) c) c) c) c) c) c)	$\begin{array}{c} c_{1} \\ c_{1} \\ c_{2} \\ c_{3} \\ c_{4} \\ c_{5} \\ c_{5} \\ c_{7} \\$	a - 1		Ū.	1 <u>4</u>		
	MILLIN	IETERS	INCHES				MILLIN	METERS IN		ICHES	
DIM.	MIN.	MAX.	MIN.	MAX.		DIM.	MIN.	MAX.	MIN.	MAX.	
А	4.06	4.83	0.160	0.190		D1	6.86	-	0.270	-	
				0.010		-		10.07	0.000	0.420	
A1	0.00	0.25	0.000	0.010		E	9.65	10.67	0.380	0.120	
A1 b	0.00 0.51	0.25 0.99	0.000	0.010		E1	9.65 6.22	- 10.67	0.380	-	
							6.22	- 10.67 - BSC	0.245	- BSC	
b	0.51	0.99	0.020	0.039		E1	6.22	-	0.245	-	
b b1	0.51 0.51	0.99 0.89	0.020 0.020	0.039 0.035		E1 e	6.22 2.54	- BSC	0.245	-) BSC	
b b1 b2	0.51 0.51 1.14	0.99 0.89 1.78	0.020 0.020 0.045	0.039 0.035 0.070		E1 e H	6.22 2.54 14.61	- BSC 15.88	0.245 0.100 0.575	-) BSC 0.625	
b b1 b2 b3	0.51 0.51 1.14 1.14	0.99 0.89 1.78 1.73	0.020 0.020 0.045 0.045	0.039 0.035 0.070 0.068		E1 e H L	6.22 2.54 14.61 1.78	- BSC 15.88 2.79	0.245 0.100 0.575 0.070	- 0 BSC 0.625 0.110	
b b1 b2 b3 c	0.51 0.51 1.14 1.14 0.38	0.99 0.89 1.78 1.73 0.74	0.020 0.020 0.045 0.045 0.015	0.039 0.035 0.070 0.068 0.029		E1 e H L L1	6.22 2.54 14.61 1.78 - -	- BSC 15.88 2.79 1.65	0.245 0.100 0.575 0.070 - -	- 0 BSC 0.625 0.110 0.066	
b b1 b2 b3 c c1	0.51 0.51 1.14 1.14 0.38 0.38	0.99 0.89 1.78 1.73 0.74 0.58	0.020 0.020 0.045 0.045 0.015 0.015	0.039 0.035 0.070 0.068 0.029 0.023		E1 e H L L1 L2	6.22 2.54 14.61 1.78 - -	- BSC 15.88 2.79 1.65 1.78	0.245 0.100 0.575 0.070 - -	- 0 BSC 0.625 0.110 0.066 0.070	

А

Notes

1. Dimensioning and tolerancing per ASME Y14.5M-1994.

2. Dimensions are shown in millimeters (inches).

3. Dimension D and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outmost extremes of the plastic body at datum A.

4. Thermal PAD contour optional within dimension E, L1, D1 and E1.

5. Dimension b1 and c1 apply to base metal only.

6. Datum A and B to be determined at datum plane H.

7. Outline conforms to JEDEC outline to TO-263AB.



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RECOMMENDED MINIMUM PADS FOR D²PAK: 3-Lead



Recommended Minimum Pads Dimensions in Inches/(mm)

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